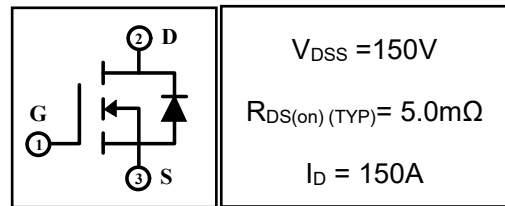


## 150A 150V N-channel Enhancement Mode Power MOSFET

### 1 Description

These N-channel enhancement mode power MOSFET utilizes advanced Split Gate Trench technology, which provides excellent  $R_{DS(on)}$  and low Gate charge at the same time. Which accords with the RoHS standard.

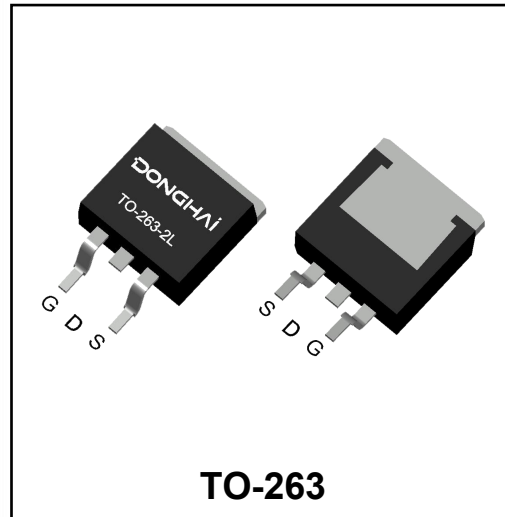


### 2 Features

- Low on resistance
- Low gate charge
- Fast switching
- Low reverse transfer capacitances
- 100% single pulse avalanche energy test
- 100%  $\Delta V_{DS}$  test
- **AEC-Q101 qualified**

### 3 Applications

- Motor control and drive
- Battery management
- UPS (Uninterruptible Power Supplies)



### 4 Electrical Characteristics

#### 4.1 Absolute Maximum Ratings (T<sub>c</sub>=25°C, unless otherwise noted)

Parameter		Symbol	Rating	Units
Drain-to-Source Voltage		$V_{DSS}$	150	V
Gate-to-Source Voltage		$V_{GSS}$	±20	V
Continuous Drain Current	T <sub>c</sub> =25°C	$I_D$	150	A
	T <sub>c</sub> =100°C		104	A
Pulsed Drain Current <sup>(1)</sup>		$I_{DM}$	600	A
Single Pulse Avalanche Energy <sup>(4)</sup>		$E_{AS}$	1089	mJ
Power Dissipation	T <sub>a</sub> =25°C	$P_{tot}$	2.3	W
	T <sub>c</sub> =25°C	$P_{tot}$	300	W
Junction Temperature Range		T <sub>j</sub>	-55~175	°C
Storage Temperature Range		T <sub>stg</sub>	-55~175	°C

#### 4.2 Thermal Characteristics

Parameter	Symbol	Value			Units
		Min	Typ	Max	
Thermal Resistance, Junction to Case-sink	$R_{thJC}$	—	0.35	0.5	°C/W
Thermal Resistance, Junction to Ambient	$R_{thJA}$	—	50	65	°C/W

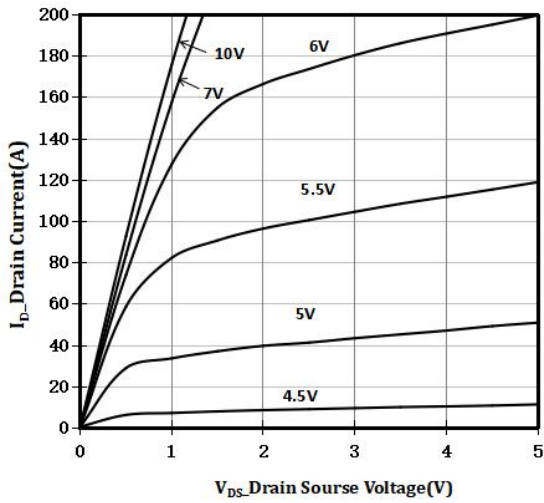
**4.3 Electrical Characteristics** (Tc=25°C, unless otherwise noted)

Parameter	Symbol	Test Condition	Value			Units
			Min	Typ	Ma	
<b>Off Characteristics</b>						
Drain-to-Source Breakdown Voltage	$BV_{DSS}$	$I_D=250\mu A, V_{GS}=0V$	150	--	--	V
Drain-to-Source Leakage Current	$I_{DSS}$	$V_{DS}=150V, V_{GS}=0V, T_C=25^\circ C$	--	--	1	$\mu A$
		$V_{DS}=150V, V_{GS}=0V, T_C=125^\circ C$	--	--	100	$\mu A$
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	--	--	$\pm 100$	nA
<b>On Characteristics</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	2	3	4	V
Drain-to-Source on-state Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=60A$	--	5.0	5.8	m $\Omega$
<b>Dynamic Characteristics</b>						
Input Capacitance	$C_{iss}$	$V_{GS}=0V, V_{DS}=75V, f=1.0MHz$	--	7781	--	pF
Output Capacitance	$C_{oss}$		--	611	--	
Reverse Transfer Capacitance	$C_{rss}$		--	21	--	
Gate Resitance	$R_G$	$V_{DS}=0V, V_{GS}=0V, F=1MHz$	--	0.9	--	$\Omega$
<b>Switching Characteristics</b>						
Turn-on Delay Time	$t_{d(on)}$	$V_{GS}=10V, V_{DS}=75V, I_D=60A, R_G=3\Omega$	--	26	--	nS
Turn-on Rise Time	$t_r$		--	38	--	
Turn-off Delay Time	$t_{d(off)}$		--	46	--	
Turn-off Fall Time	$t_f$		--	25	--	
Total Gate Charge	$Q_g$	$I_D=70A, V_{DS}=75V, V_{GS}=10V$	--	112	--	nC
Gate-to-Source Charge	$Q_{gs}$		--	41	--	
Gate-to-Drain("Miller") Charge	$Q_{gd}$		--	32	--	
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(3)</sup>	$V_{SD}$	$V_{GS}=0V, I_S=60A$	--	--	1.2	V
Diode Forward Current	$I_S$		--	--	150	A
Reverse Recovery Time <sup>(3)</sup>	$t_{rr}$	$T_J=25^\circ C, I_F=60A$	--	95	--	nS
Reverse Recovery Charge <sup>(3)</sup>	$Q_{rr}$	$dI_F/dt=100A/\mu S, V_{GS}=0V$	--	289	--	nC

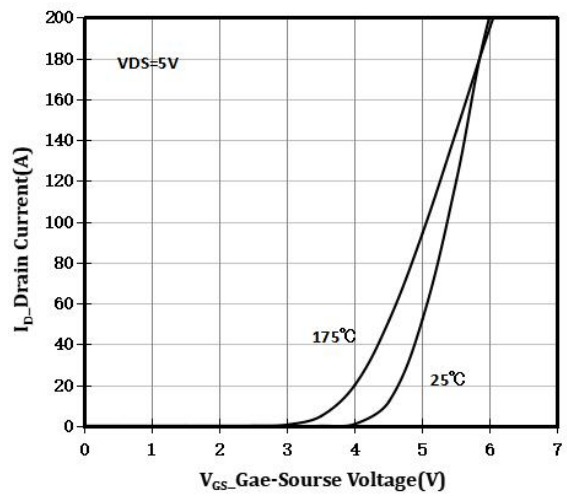
**Notes:**

- 1: Repetitive rating, pulse width limited by maximum junction temperature.
- 2: Surface mounted on FR4 Board,  $t_s \leq 10sec$ .
- 3: Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
- 4:  $L=0.5mH, V_{DD}=50V, V_G=150V, Start T_J=25^\circ C$ .

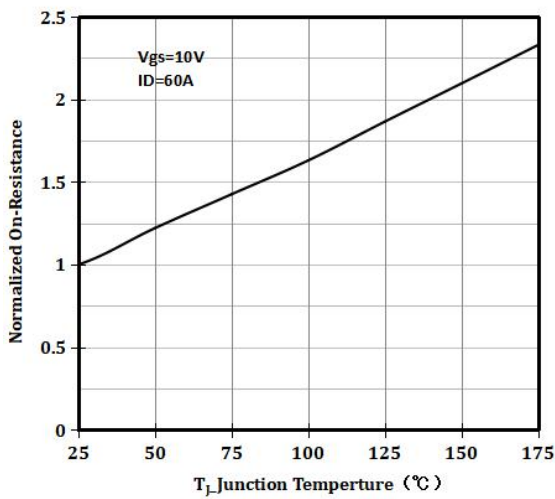
**5 Typical characteristics diagrams**



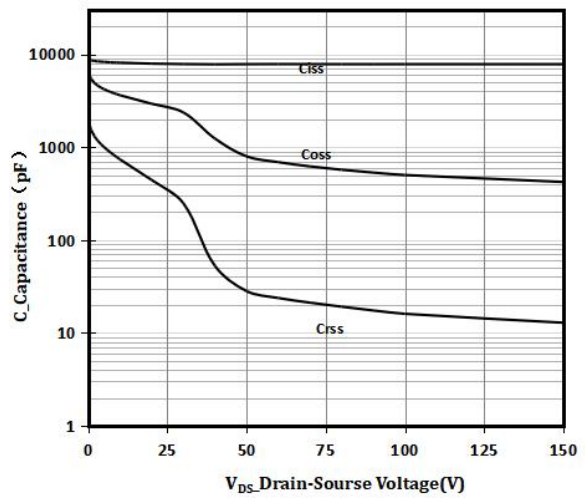
**Fig 1 Output Characteristics**



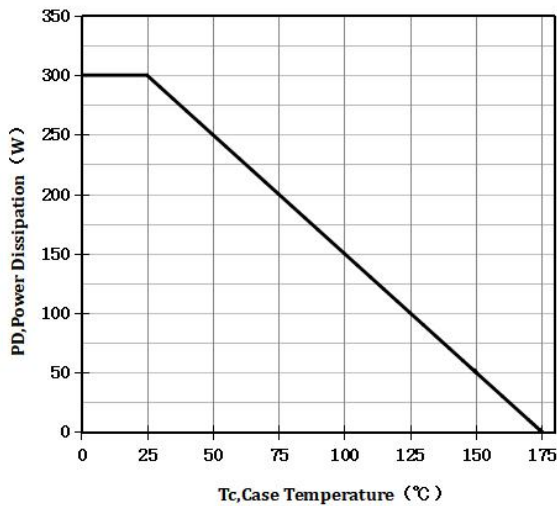
**Fig 2 Transfer Characteristics**



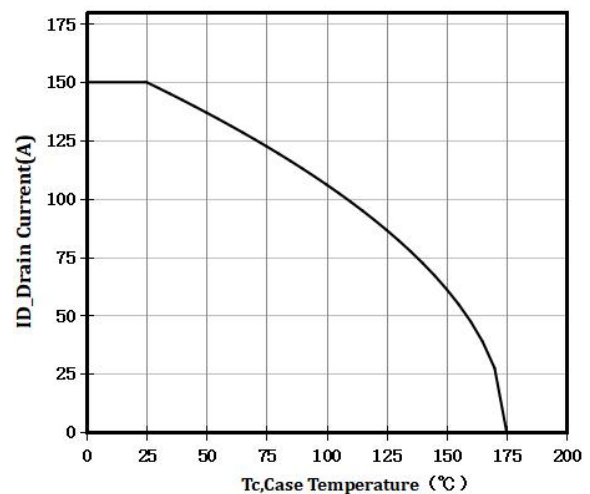
**Fig 3 RDSON vs Junction Temperature**



**Fig 4 Capacitance vs Vds**

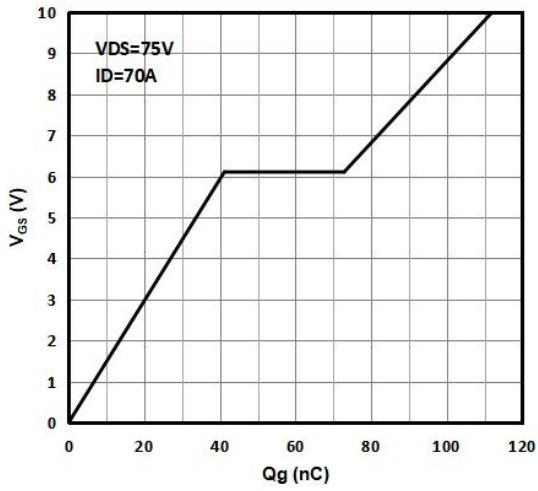


**Fig 5 Power De-rating**

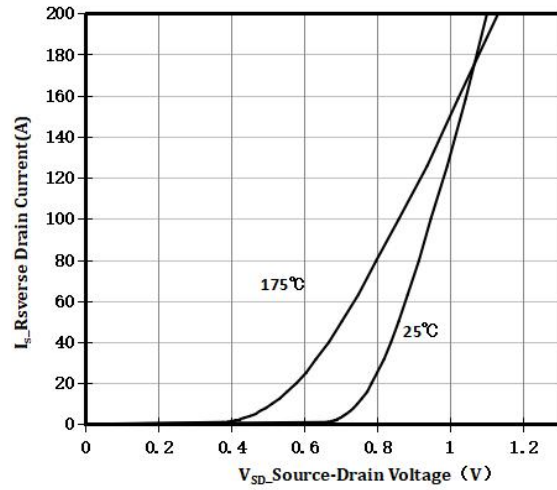


**Fig 6 ID Current De-rating**

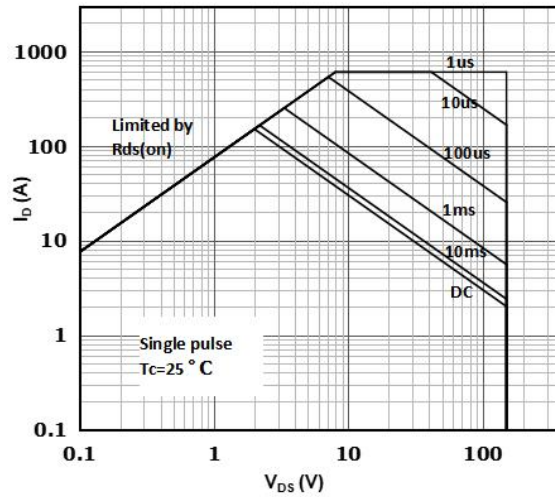
**5 Typical characteristics diagrams(continues)**



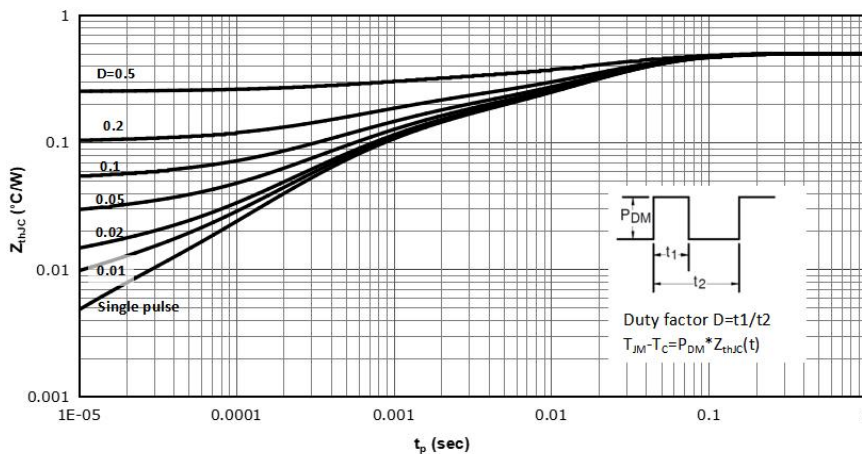
**Fig 7 Gate Charge Figure**



**Fig 8 Source-Drain Diode Forward**

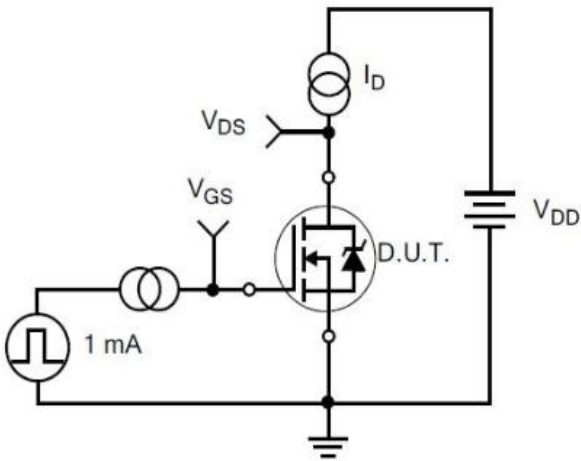


**Fig 9 SOA**

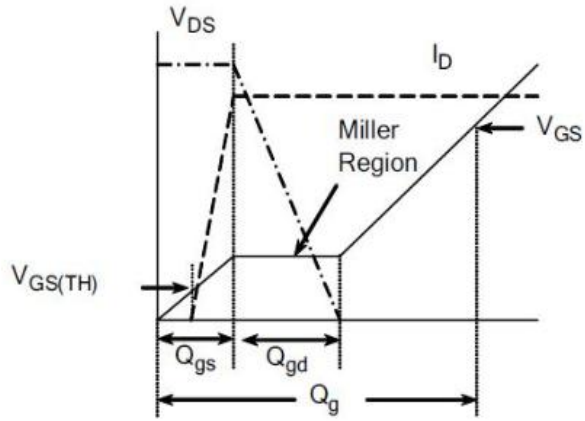


**Fig 10 Normalized Maximum Transient Thermal Impedance**

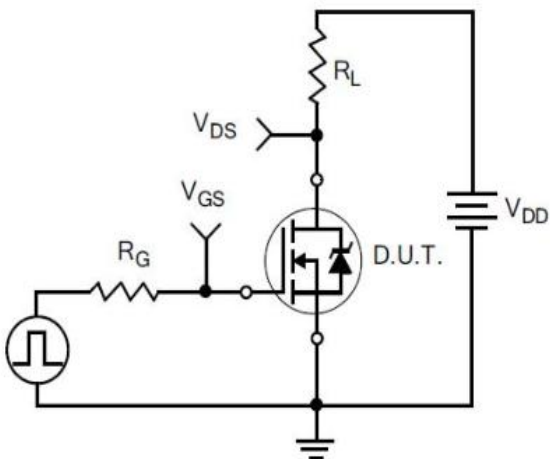
**6 Typical Test Circuit and Waveform**



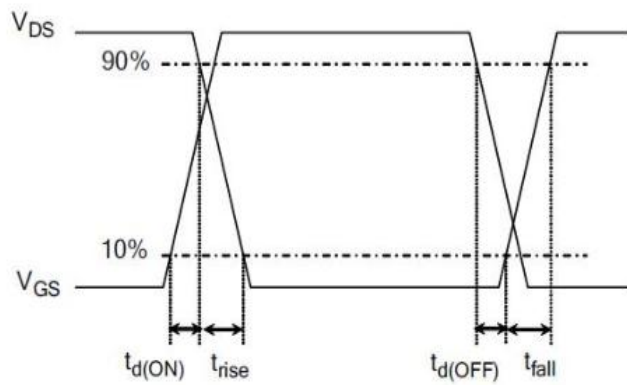
1) Gate Charge Test Circuit



2) . Gate Charge Waveform

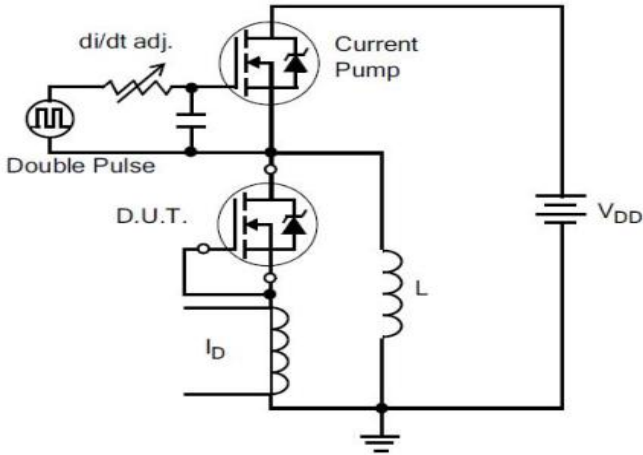


3) Resistive Switching Test Circuit

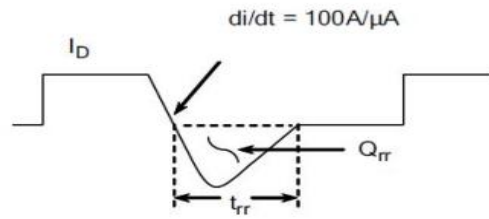


4) Resistive Switching Waveforms

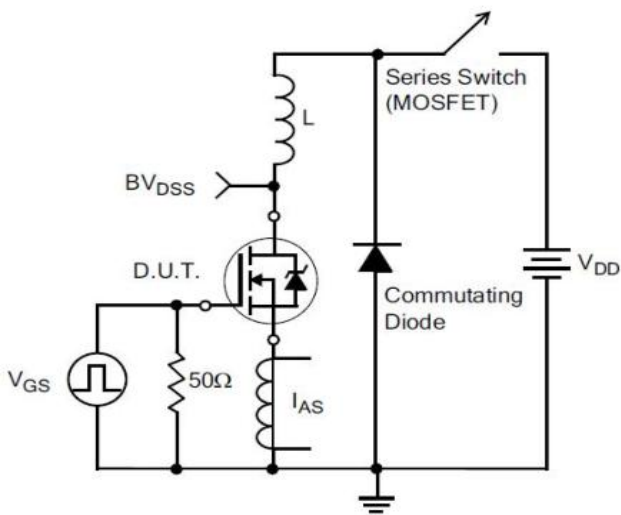
**6 Typical Test Circuit and Waveform(continues)**



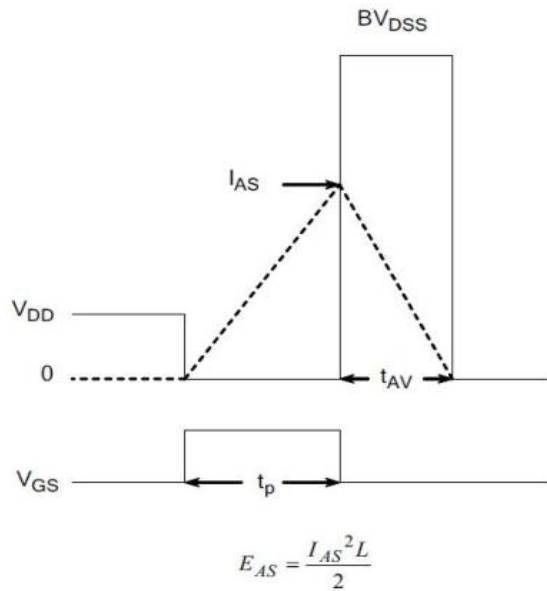
5) Diode Reverse Recovery Test Circuit



6) Diode Reverse Recovery Waveform

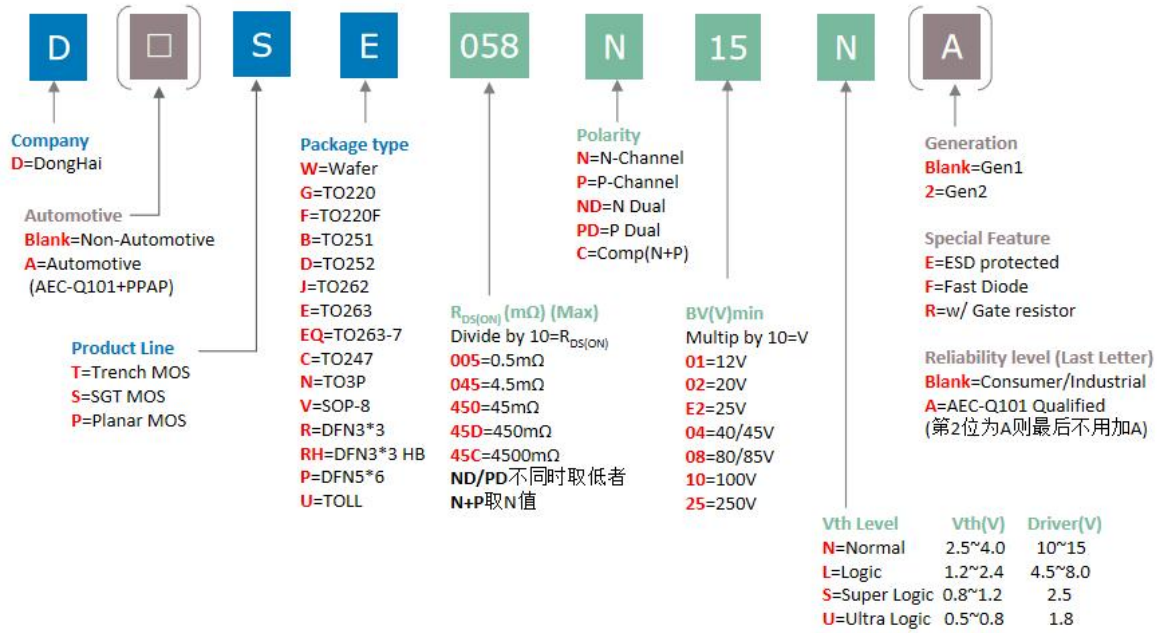


7) . Unclamped Inductive Switching Test Circuit



8) Unclamped Inductive Switching Waveforms

## 7 Product Names Rules



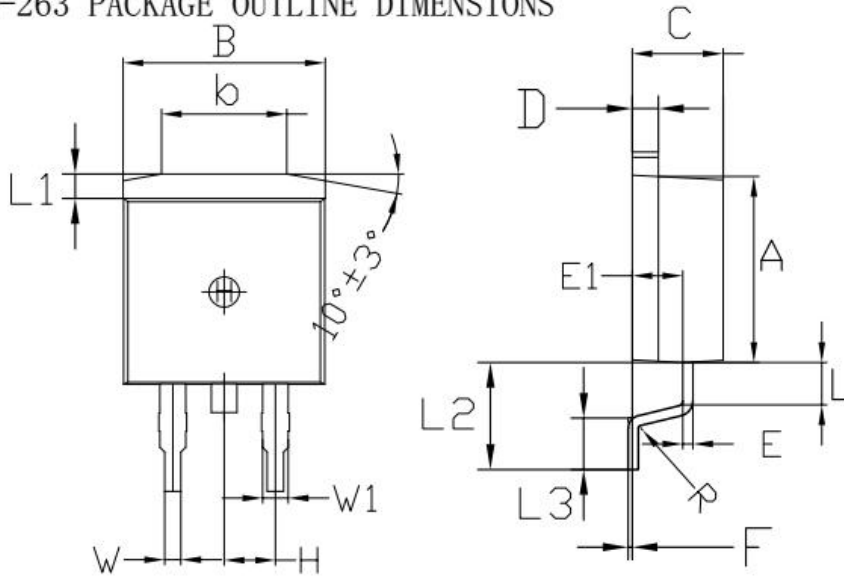
## 8 Product Specifications and Packaging Models

Product Model	Package Type	Mark Name	RoHS	Package	Quantity
DSE058N15NA	TO-263	DSE058N15NA	Pb-free	Tape & Reel	800/box



9 Dimensions

TO-263 PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	min.	max.	min.	max.
A	8.80	9.30	0.346	0.366
B	9.70	10.30	0.382	0.406
C	4.25	4.75	0.167	0.187
D	1.20	1.45	0.047	0.057
E	0.40	0.60	0.016	0.024
L	1.90	2.30	0.075	0.091
L1	1.15	1.45	0.045	0.057
R	0.24	0.26	0.0095	0.0102
W	0.80	0.82	0.0315	0.0323
W1	1.20	1.30	0.047	0.051
H	2.54 TYP		0.200 TYP	
b	5.50	6.50	0.216	0.256
E1	2.4	2.6	0.0946	0.1024
L2	5.20	5.80	0.205	0.228
L3	2.20	3.20	0.087	0.126
F	0.03	0.23	0.0012	0.0091



## 10 Attentions

- Jiangsu Donghai Semiconductor Technology CO.,LTD. reserves the right to change the specification without prior notice! The customer should obtain the latest version of the information before making the order and verify that the information is complete and up to date.
- It is the responsibility of the purchaser for any failure or failure of any semiconductor product under certain conditions. It is the responsibility of the purchaser to comply with safety standards and to take safety measures in the system design and machine manufacturing of Donghai products in order to avoid potential risk of failure. Injury or property damage.
- Product promotion is endless, our company will be dedicated to provide customers with better products.

## 11 Appendix

Revision history:

Date	REV.	Description	Page
2022.11.05	1.0	Original	9
2023.7.20	2.0	Update Cap and Qg	P2